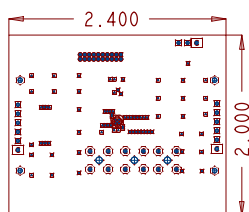


NOTES:

1. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-2221 BOARD TYPE 3, PERFORMANCE CLASS 2, AND IPC-A-600 UNLESS SPECIFIED BELOW.
2. MATERIAL - EPOXY GLASS .062 TOTAL THICKNESS +/- 10%, FR4, 1 OZ COPPER.
3. IMMERSION GOLD. 3-5 MICRO INCHES
4. FRONT TO BACK REGISTRATION TO BE WITHIN .005.
5. THE DIAMETER DIMENSION OF ALL PLATED THRU HOLES APPLY AFTER PLATING.
6. ELECTROPLATED COPPER SHALL BE USED FOR PLATED THRU HOLES, AND SHALL HAVE A MINIMUM THICKNESS OF .001 ON THE HOLE WALLS.
7. SOLDER MASK BOTH SIDES USING RED IAW IPC-SM-840.
8. SILKSCREEN BOTH SIDES WITH WHITE NON CONDUCTIVE EPOXY BASED INK.
9. MARK DATE CODE AND MANUFACTURERS IDENTIFICATION ON SOLDER SIDE PER IPC RB 276.
10. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY.



Drill Chart

4 Layer Stack-up

Layer Order	Layer Name	Material Type	Thickness (Mils)	Copper Weight
1	Top	Copper	1.4	1 oz
		Prepreg	4	
2	Layer 2	Copper	1.4	1 oz
		Core	48.4	
3	Layer 3	Copper	1.4	1 oz
		Prepreg	4	
4	Bottom	Copper	1.4	1 oz

Final Board Thickness: 42 +/- 10%

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	PLATED	QTY
⊙	8.0	PLATED	5
×	8.0	PLATED	6
×	10.0	PLATED	70
•	23.0	PLATED	19
×	23.0	PLATED	1
⊞	36.0	PLATED	12
⊞	36.0	PLATED	3
⊞	37.0	PLATED	12
⊞	50.0	PLATED	4
⊞	73.0	PLATED	3

PHYSICAL BOARD DIMENSIONS & LAYER STRUCTURE

↓	SILK TOP	silkt.art
↓	MASK TOP	smaskt.art
↓	COMPONENT	Top.art (1oz)
↓	LAYER 2	layer2.art (1oz)
↓	LAYER 3	layer3.art (1oz)
↓	SOLDER	Bottom.art (1oz)
↓	MASK BOTTOM	smaskb.art
↓	SILK BOTTOM	silkb.art

ENGINEER:	BRAD SUPPANZ	DRAWN BY:	PHUONG CAO	BOARD NUMBER:	ISL9122AIR-EVZ
RELEASED BY:	BRAD SUPPANZ	DATE DRAWN:	08/09/2017		1001 MURPHY RANCH ROAD
UPDATED BY:		DATE RELEASED:	09/08/2017		MILPITAS CA 95035
intersil		MASK#	HWNR ID	REV.	
		FILENAME:	ISL9122AIR-EVZ_LAYOUT	B	
		FILENAME:	ISL9122AIR-EVZ_LAYOUT	SHEET	1